

## ICGEE Curriculum available for 2011/2012 Academic Year

### Microelectronics Technology

<b>Module Title:</b>	Microelectronics Technology
<b>Module Status:</b>	Available, running in the 2011/2012 academic year, starting from middle October to middle December

#### **Generic Module Information:**

<b>Name of module owner/lecturer?</b>	Dr. Tatiana Perova
<b>Delivery mode: e.g. on-site, on-line, mixed-mode. For on-site specify contact hours per week</b>	<p><b>For Dublin located students:</b> On-site 1.5 hours lectures per week, 1 hour average laboratory per week</p> <p><b>For students from other locations:</b> 3 days intensive block delivery workshop combined with lectures and laboratory work, on-site in TCD</p>
<b>Duration of the module:</b>	1 Semester
<b>Assessment methods and weightings where relevant:</b>	End of semester exam (85%) plus laboratory continuous assessment (15%)
<b>Pass standard:</b>	Demonstration of good activities during the experimental work and mark for the report minimum 40%.
<b>Penalties for late submission of continuous assessment work:</b>	Penalties for late submission of continuous assessment work: reduction of the overall mark
<b>Number of ECTs or institutional credits assigned to the module:</b>	5 ECTs
<b>Course Content or Syllabus (Optional):</b>	<ul style="list-style-type: none"> <li>• Processing techniques: The following techniques will be examined in some detail: crystal growth; diffusion; ion-implantation; oxidation; lithography; metallisation; plasma etching.</li> <li>• Spectroscopy: Brief introductory material on application of Fourier Transform Infrared (FTIR) and Raman spectroscopy to IC technology will be presented.</li> <li>• Devices/Circuits: Techniques for fabrication of the following devices, using the processing techniques described above, will be studied:</li> <li>• Bipolar: discrete transistor; monolithic IC transistor; resistor; diode; capacitor; circuit layout for ECL NOR gate. MOS: PMOS, NMOS and CMOS technologies will be introduced and the problem of latch-up will be discussed.</li> <li>• Silicon-on-Insulator will be proposed as an alternative to bulk silicon.</li> </ul>
<b>Learning Outcomes</b>	<p>On successful completion of this module the learner will be able to:</p> <ul style="list-style-type: none"> <li>• The course provides the students with an opportunity to fabricate a simple PMOS integrated circuit in Microelectronic Technology Laboratory.</li> <li>• The device contains transistors, a resistor, a capacitor and two logic devices.</li> <li>• During the laboratory course the participants will acquire and appreciation of the various stages in the fabrication of</li> </ul>

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	<p>the device.</p> <ul style="list-style-type: none"> <li>• This will include wafer cleaning, field oxidation, the photolithography process, window etching, diffusion, gate oxidation and metallization.</li> <li>• The participants are also fully trained in the safe handling of chemicals. The final part of the course consists of a lecture on device testing and packaging in the lab.</li> </ul>
<b>Recommended Text</b>	<ul style="list-style-type: none"> <li>• S.M. Sze, Semiconductor Devices; Physics and Technology, John Willey &amp; Sons, Inc., USA, 2002 (or any later edition)</li> <li>• J.D. Plummer, M.D. Deal, and P. B. Griffin, Silicon VLSI Technology, Prentice Hall, NY, 2000 (or any later edition).</li> <li>• B.G. Streetman, S. K. Banerjee, Solid State Electronic Devices, Pearson, Prentice Hall, New Jersey, 2000 (or any later edition).</li> </ul>
<b>Supplementary Texts</b>	Handouts and Power Point Presentation will be provided at the site.